

# FutureHorizons



The Global Semiconductor Industry Analysts

## FH MONDAY

31 October 2022

Globalfoundries receives \$30 GaN semiconductor contract

Globalfoundries has received a \$30 million federal funding award for the development and production of next-generation gallium nitride (GaN) on silicon semiconductors.

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Cadence expands deal with Samsung on 3D-IC design

Cadence Design Systems Inc. has expanded its collaboration with Samsung Foundry to accelerate the use of 3D-IC design. As part of the deal, the reference flow featuring Cadence Integrity 3D-IC platform will help to create next generation hyperscale computing, mobile, automotive and artificial intelligence (AI) applications.

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Apple sees iPhone growth as overall smartphone market slips

Smartphones declined for a third consecutive quarter, marking the worst Q3 since 2014. Only Apple showed positive growth of the top five vendors as the overall market dropped by 9% compared to a year earlier,

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TALK TO US



Ceremorphic Successfully Tapes Out First 5nm AI Supercomputing Chip

Ceremorphic Inc. has successfully taped out its first 5nm chip with its partner Taiwan Semiconductor Manufacturing Co. Ltd (TSMC). As the only AI supercomputing chip to solve the high-performance computing needs in reliability, security and power consumption at scale, the Ceremorphic solution delivers the performance required for next-generation applications such.....

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### EVENTS

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- March 2023- London UK

[Industry Forecast Briefing](#)

- January 2023- London UK

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Infineon Enables the 10-minute IoT Experience

Infineon Technologies AG has launched a new IoT sensor platform for rapid prototyping and development of customized IoT solutions. Based on a combination of XENSIV sensors with power-efficient, high-performance processing based on the PSoC 6 microcontroller (MCU), the XENSIV connected sensor kit (CSK) utilizes Infineon's products and offers ready-to-use sensor scenarios

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## **Globalfoundries Receives \$30 Gan Semiconductor Contract**

Globalfoundries has received a \$30 million federal funding award for the development and production of next-generation gallium nitride (GaN) on silicon semiconductors.

The funding was part of the Consolidated Appropriations Act for Fiscal Year 2022 secured by U.S. Senator Patrick Leahy. As part of the funding, GF will be able to purchase tools and extend development and implementation of 200 mm GaN wafer manufacturing.

The GaN semiconductors will be manufactured at GF's Essex Junction, Vermont, facility. The fab, which is located near Burlington, was one of the first major semiconductor manufacturing sites in the U.S. and manufactures more than 600,000 wafers per year.

## **Cadence Expands Deal With Samsung On 3D-IC Design**

As part of the deal, the reference flow featuring Cadence Integrity 3D-IC platform will help to create next generation hyperscale computing, mobile, automotive and artificial intelligence (AI) applications.

The power, performance and area (PPA) of the 3D-IC can be impacted when chips are stacked in a 3D-IC configuration instead of in a 2D configuration due to the presence of large 3D structures such as TSVs, which connect the stacked chips.

Cadence's Integrity 3D-IC platform lets users create multiple TSV insertion scenarios and device an optimal 3D structure placement on a die with reduced wirelength penalties while boosting PPA and productivity, Cadence said.

## **Apple Sees Iphone Growth As Overall Smartphone Market Slips For Third Straight Quarter**

Smartphones declined for a third consecutive quarter, marking the worst Q3 since 2014. Only Apple showed positive growth of the top five vendors as the overall market dropped by 9% compared to a year earlier, according to Canalys.

Amid a gloomy economic outlook, consumers are delaying purchases of electronics, the analyst firm said. Demand shows no signs of improving through June of next year, said Canalys Analyst Sanyam Chaurasia.

In this webinar, we discuss how patients, pharma companies and other stakeholders benefit from accelerating NFC digitization and internet-connectivity. Smarter medicine packaging can secure products through digital authentication and promote patient engagement. Connected drug delivery products add value through improved medication adherence and outcome optimization.

IDC recently noted a similar trend with PCs, with Q3 marking the third straight quarter of declines and dropping by 15% over a year earlier.

## **Ceremorphic Successfully Tapes Out First 5nm AI Supercomputing Chip**

Ceremorphic Inc. has successfully taped out its first 5nm chip with its partner Taiwan Semiconductor Manufacturing Co. Ltd (TSMC). As the only AI supercomputing chip to solve the high-performance computing needs in reliability, security and power consumption at scale, the Ceremorphic solution delivers the performance required for next-generation applications such as AI model training, HPC, drug discovery and metaverse processing.

"Ceremorphic is the first company to tape out an AI supercomputing chip in the advanced 5nm process node, which represents a significant accomplishment for our company," said Dr. Venkat Mattela, Founder and CEO of Ceremorphic. "Our hardware and software engineering teams have once again proven to be world-class and this design achievement positions us well for our next phase of growth and expansion."

## **Infineon Enables the 10-minute IoT Experience with Connected Sensor Kit**

Infineon Technologies AG has launched a new IoT sensor platform for rapid prototyping and development of customized IoT solutions. Based on a combination of XENSIV sensors with power-efficient, high-performance processing based on the PSoC 6 microcontroller (MCU), the XENSIV connected sensor kit (CSK) utilizes Infineon's products and offers ready-to-use sensor scenarios and quick data visualization to enable the 10-minute IoT experience.

According to Ivan Karan of the Application Marketing IoT & Sensor Solutions Team at Infineon, combining all components—the sensors, MCUs, and modules for connectivity—is difficult and is very rare in the market.